ThermalTIG0350LV

TDS A1 2025.11



Thermal TIG0350LV

Features

- Low Thermal Resistance
- Low Viscosity
- High Reliability
- Screen Printing

Applications

- Laptop CPU CPU
- Communication equipment
- Power supply controller
- ADAS

[redacted]	Typical Value	Unit	Test Method
Composition	Silicone Filled with Thermal Powder &		—
Color			
Viscosity @1s[1]			
Bond-line Thickness (BLT	35		—
Density	3.1	g/cm^3	ASTM D792
Temperature Range	-40 - 150	℃	—
Breakdown Voltage	3.5	KV/mm	ASTM D149

All technical information stated in this technical data have been confirmed that all the technical parameters are reliable after harsh testing and evaluation of the products. Before you use our products, please carefully evaluate and decide whether the product meets your requirement and you need to take all the risks and responsibilities to use.